



# Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures

Marketing Name / Model

[List multiple models if applicable.]

HP Disk System 2500 Enclosure AG572A

AD542A (M5314 FC Drive Encl). AD542B (HP M5314B FC Drive Enclosure, AD542C (HP M5314C FC Drive Enclosure)

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	14
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		20
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing		

radioactive substances		
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
No 2 Philips screw diver, Long Allen wrench 5/32	2
No 2 Philips screw diver, Long Allen wrench 5/32	2
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassemble the power supply using No. 2 philips screw driver. Remove 10 electrolytic capacitors measuring 2.cm in diameter or height for each power supply.
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Capacitors needing removal.

